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Part Number:

0738000000

Status:

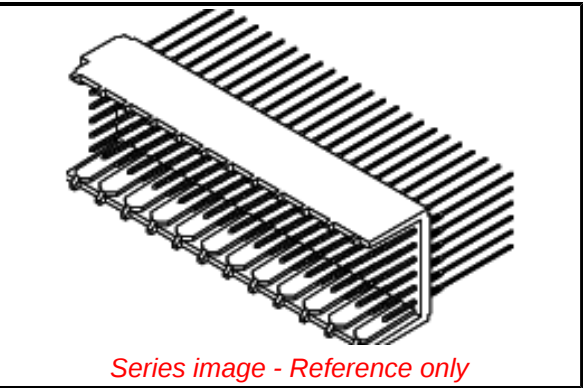
Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Midplane Header, Vertical, SMC, Press-Fit, Long Pin, Open End Option, 72 Circuits



Documents:	
3D Model	Packaging Specification PK-70873-0868 (PDF)
3D Model (PDF)	Test Summary TS-73670-990-001 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)
Product Specification PS-73780-999-001 (PDF)	

Agency Certification	
CSA	LR19980
UL	E29179
General	
Product Family	Backplane Connectors
Series	73800
Application	Midplane
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800755946352
Physical	
Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Net Weight	4.163/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	11.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	4.00mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.051µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Electrical	

EU ELV	
Not Relevant	
EU RoHS	China RoHS
Compliant	
REACH SVHC	
Not Contained Per - ED/71/2019 (16 July 2019)	
Halogen-Free	
Status	
Low-Halogen	
For more information, please visit Contact US	
China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

73800 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling FAQ	
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.	
Global	
Description	Product #
Backplane Signal Insertion Module	622008502
Press-In Tool for 2.00mm Pitch HDM* Board-to-Board Backplane Header	

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC
Solder Process Data	
Lead-freeProcess Capability	N/A
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0868
Product Specification	PS-73780-999-001
Sales Drawing	SD-73800-001
Test Summary	TS-73670-990-001

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